

PLEASE AMEND THE SPECIFICATION AS INDICATED BELOW:***Page 2, paragraph beginning at line 4:***

Preferably, the contact section of the mold, which is adapted to engage with the surface of the semiconductor chip, is in the form of a removable member which is mounted on one of the mold halves, and extends through an open passage or aperture therein. Preferably, the removable member is mounted for movement relative to the mold half on which it is mounted.

Page 3, paragraph beginning at line 24:

Figure 1B shows a mold which comprises an upper mold half 6 and a lower half 7, which define a mold cavity 9. An insert 8 may be inserted through an aperture, i.e., an open passage in the upper mold half 6 so that surface 10 of the insert 8 enters the mold cavity 9. The mold cavity 9 has a distance "d" between the upper surface of the upper mold half 6 and the lower surface of the lower mold half 7. This dimension "d" is equal to the height "D" between the substrate 2 and the surface 5 of the chip 1, as shown in Figure 1A. When the semiconductor chip 1 and substrate 2 are inserted into the mold and the upper mold half is closed onto the lower mold half 7, the surface 10 of the insert 8 engages with the surface 5 of the chip 1 and as the mold halves 6, 7 are clamped shut, the force exerted by the insert 8 on the surface 5 causes the substrate 2 to flex at the bent sections 4 so that the semiconductor chip 1 is pushed downwards in the mold cavity 9 by the insert 8. This downward force exerted by the insert 8 acts to generate a sealing pressure between the surface 10 and the surface 5 so that when molding material is injected into the mold cavity 9, the molding material molds around the semiconductor chip 1, the substrate 2 and solder bumps 3 but seepage of molding material between the surfaces 5, 10 is minimised. Hence, when the molded product is removed from the mold, the portion of the surface 5 which has been contacted by the surface 10 is free of molding material and so the portion of the surface 5 which has been contacted by the surface 10 is exposed.

Page 4, paragraph beginning at line 21:

Figure 2 shows a second example of a mold which comprises an upper mold half 15 and a lower mold half 16 which define a mold cavity 17. An insert 19 may be inserted through an aperture or open passage in the upper mold half 15 so that a lower end 20 is located within the mold cavity 17. The lower end 20 comprises a profiled edge 21 which extends along the outside of the lower end 20 and engages with a surface 26 of a semiconductor chip 22 located in the mold cavity 17. A steel holder 18 encircles the insert 19 and provides a means to enable the insert 19 to be mounted on the mold.